

Connector for Memory Stick™

SCEC Series

ESD (electro-static discharge) protection model whose robust and shutter-equipped structure achieves high reliability.

For SD Memory Card

For miniSD™ Card

For microSD™ Card

For RS-MMC™

For W-SIM™

For Memory Stick Micro™

For Memory Stick™

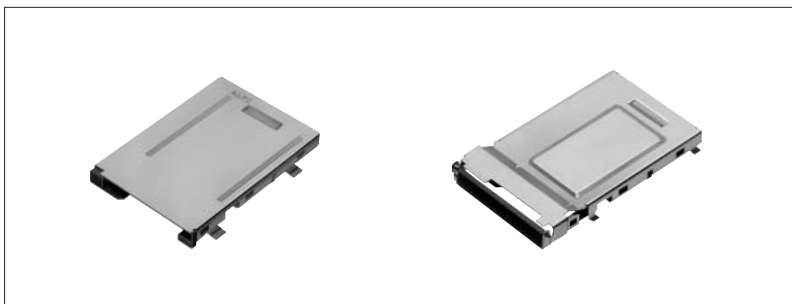
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



RoHS applicable

Features

- Long (10mm) stroke and clearly defined click for positive card insertion.
- A shutter prevents intrusion. Enclosed housing without open mouth on the top helps dust/noise prevention as well.
- Increased reliability with anti-ESD construction.
- 4 solder lug terminals are a part of the enclosure for secure mounting to the PC board.
- Allows positive Memory Stick™ locking mechanism.
- Available for reflow soldering.

Applications

- Compact portable audio equipment, desktop PCs, notebook PCs, and other information terminals
- Home audio and visual equipment (TVs, Set Top Box and recorders, etc.)

Typical Specifications

Items		Specifications
Structure	Applicable media	Memory Stick™
	Mounting method	Surface mounting type
	Mounting system	Standard mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	-20°C to +60°C
	Voltage proof	500V AC 1 minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Mating and unmating cycle	12,000 cycles

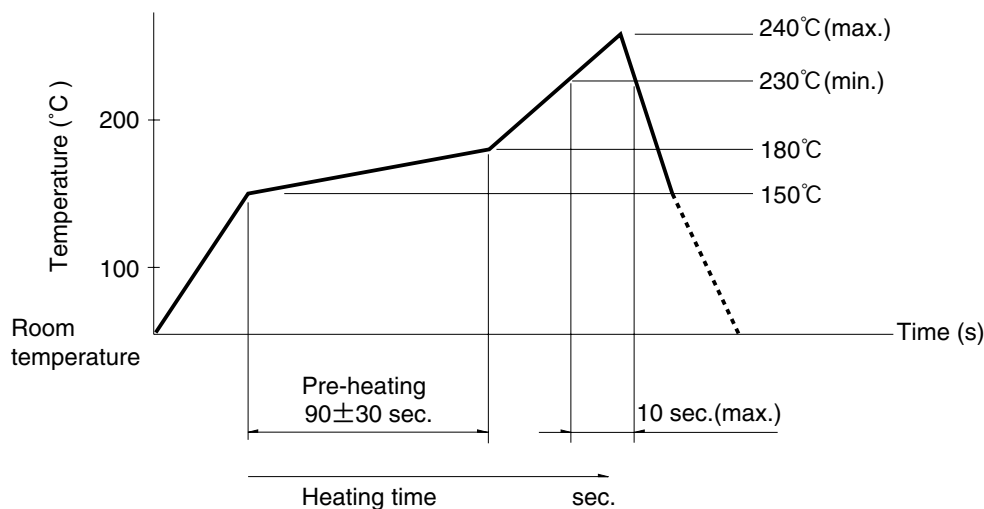
Products List

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.	Drawing No.
Push-push type	Standard mount	With boss standard mouth	0	Tray	SCEC1B0100	1
		Shutter-equipped mouse with boss			SCEC1D0100	2

Soldering Conditions

Example of Reflow Soldering Condition (Reference)

1. Heating method: Double heating method with infrared heater.
2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T).
3. Temperature profile (Surface of products).



Cautions

1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
2. When soldering, do not use water soluble flux because this may corrode the product.
3. Regarding the setting of reflow conditions, please confirm them with the actual mass production conditions.
4. As PC board warping may alter characteristics, please take this into consideration when designing pattern and layout.
5. This product has been designed and manufactured for applications to ordinary electronic equipment and devices such as the AV equipment, electric home applications, office machines and communications equipment, consequently, when employing these products for applications requiring a high degree of safety and reliability such as the medical equipment, aviation and aircraft equipment, space equipment and burglar alarm equipment, the using manufacturers will please thoroughly study the proprieties of these products for the planned applications.
6. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.

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